

Timepix array readout SRS

Michael Lupberger
University of Bonn

RD51 electronics school, 05.02.2014

Outline

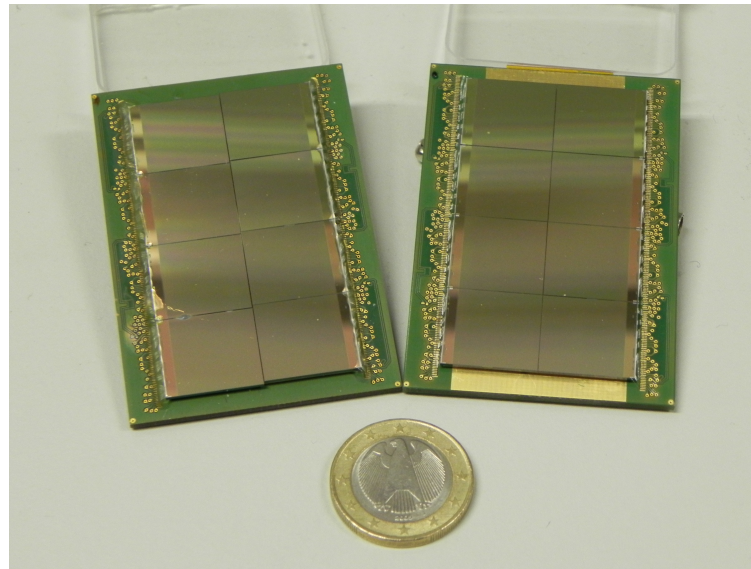
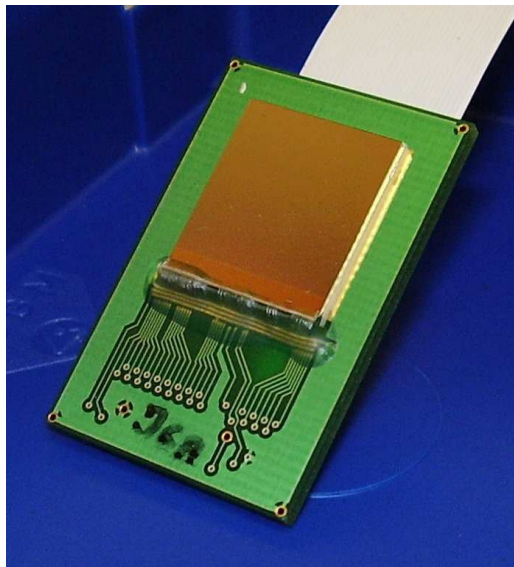


- Front end chip
- Detector
- SRS adapter card design
- FPGA Firmware

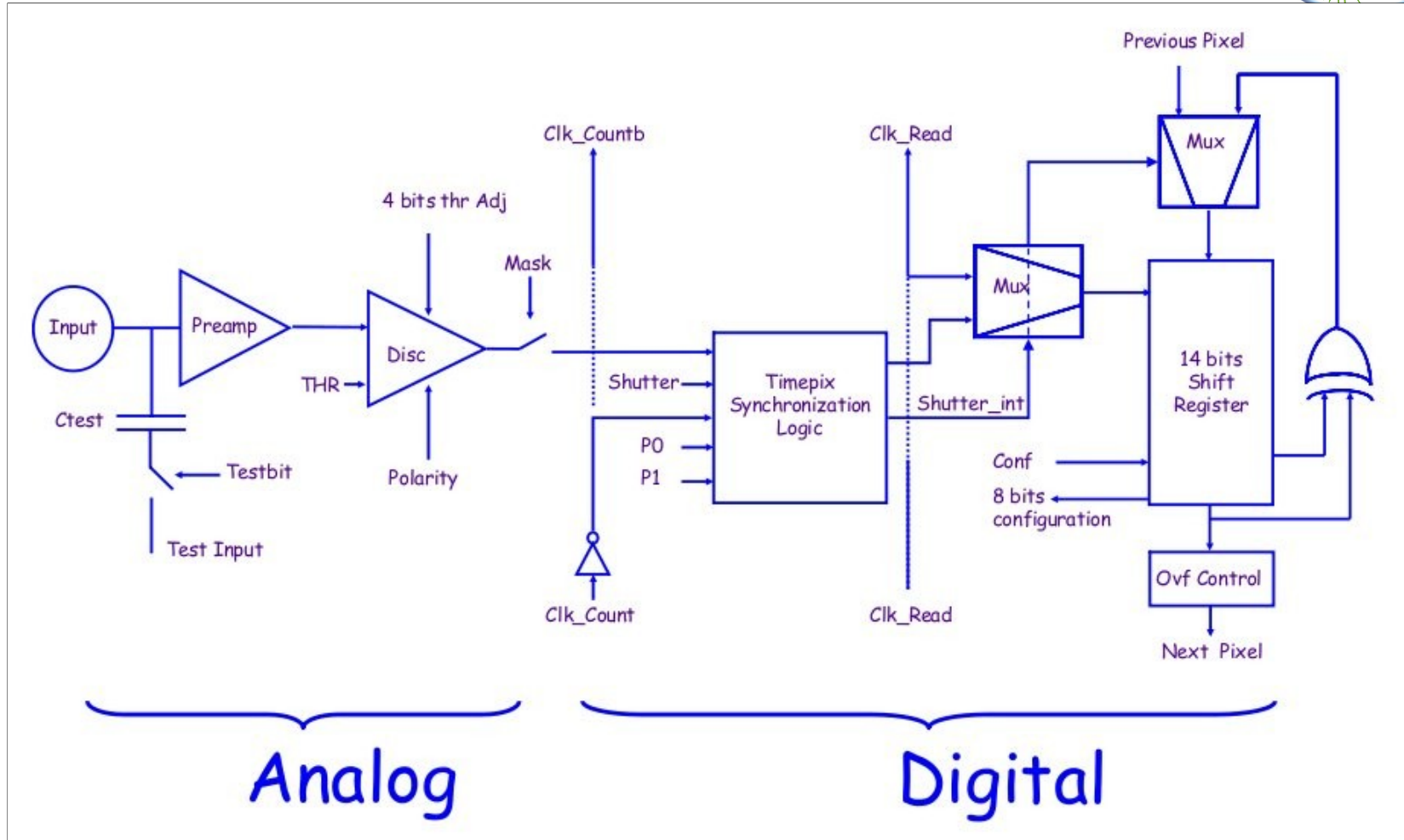
Timepix chip



- Universal readout chip
- Properties:
 - active surface: $1.4 \times 1.4 \text{ cm}^2$
 - pixel size $55 \times 55 \mu\text{m}^2$
 - 256×256 pixel array (= 65536 channels)
 - 14 bit counter in each pixel
 - Noise threshold $\sim 500e^-$ (ENC $\approx 90e^-$)



Timepix chip



Timepix chip



- 4 different modi to operate

- Medipix:

Pixel hit how often

- Time-over-threshold

Pixel hit how long

→ proportional to charge

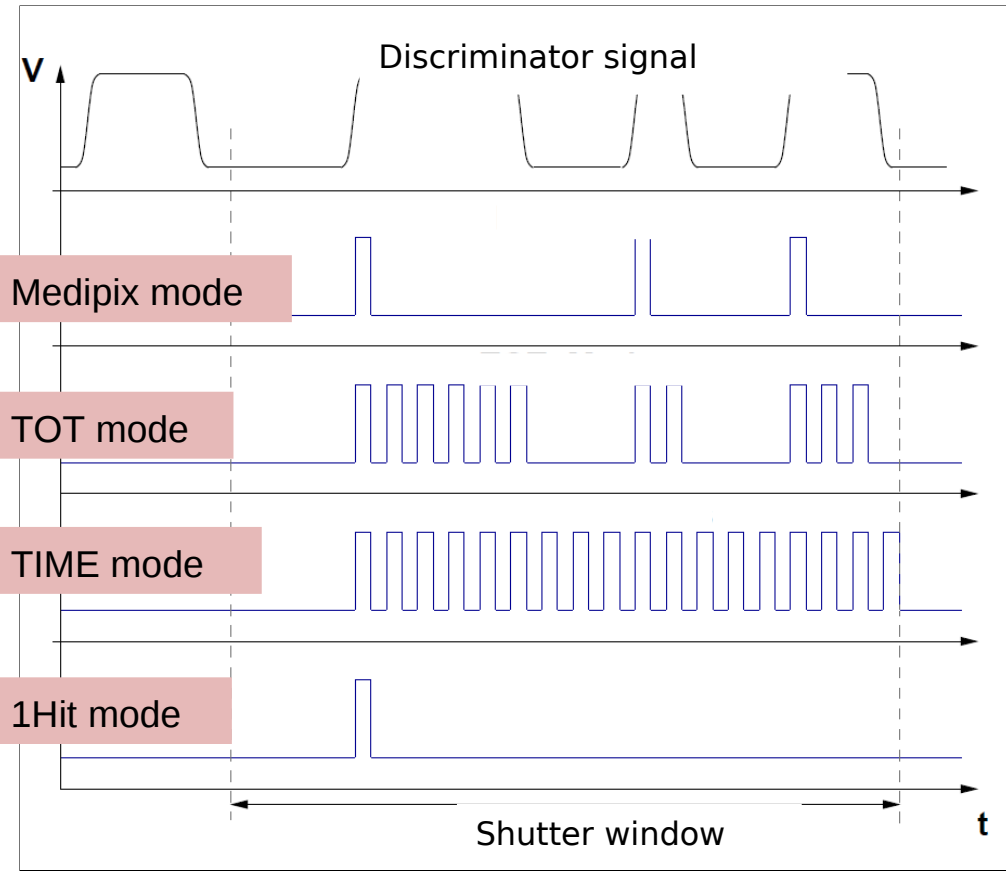
- Time:

Pixel hit when

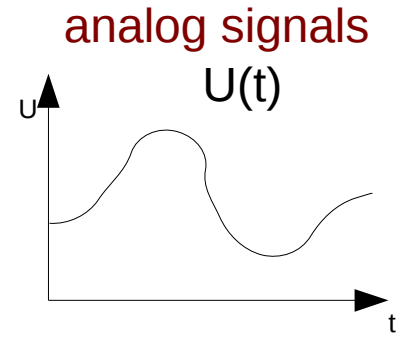
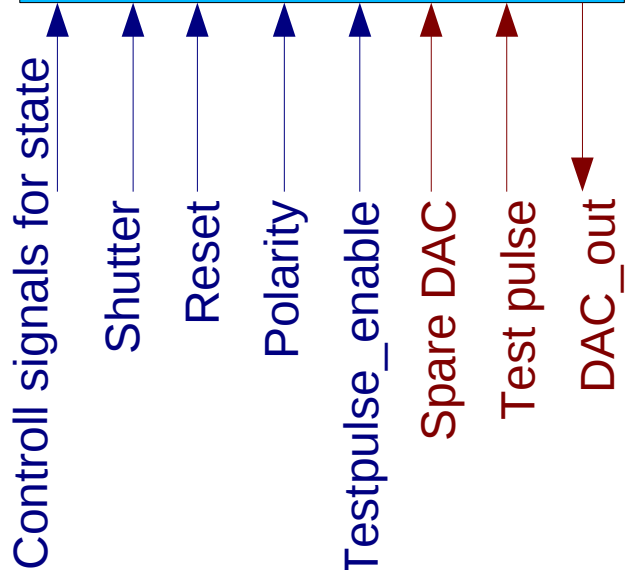
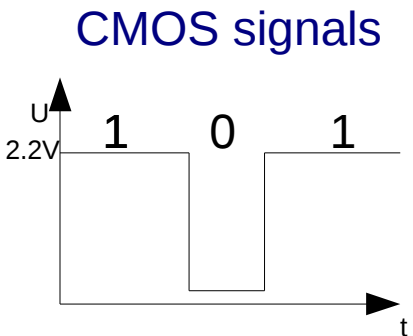
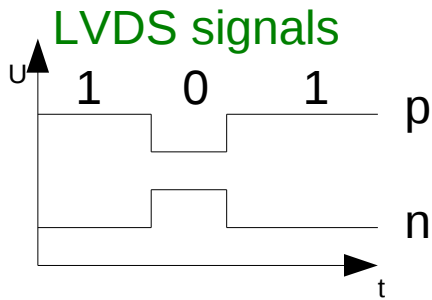
→ time of arrival

- 1Hit:

Pixel hit in shutter window



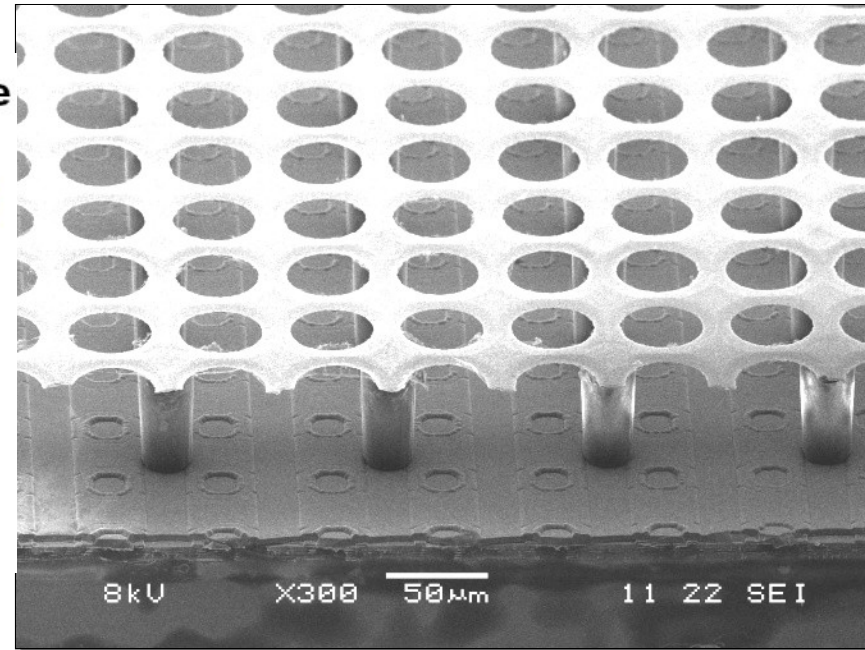
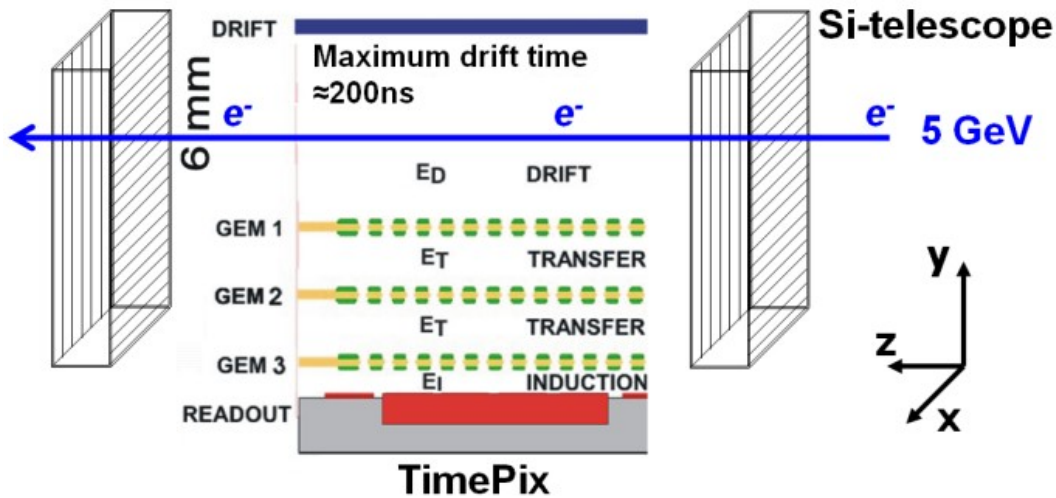
Timepix chip



Gas amplification



- Triple GEM stack
- Micromegas: InGrid

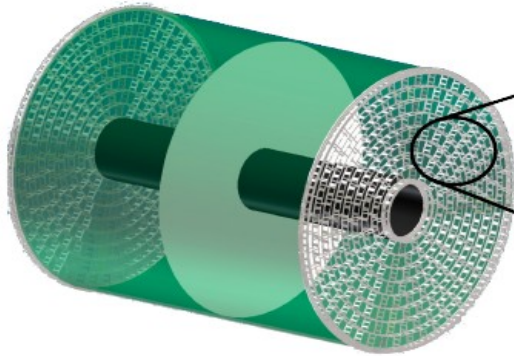


LCTPC Prototype

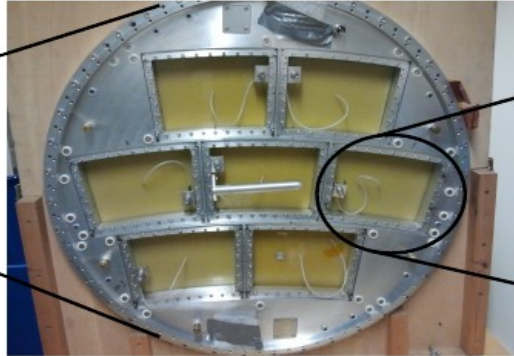


- Setup at DESY

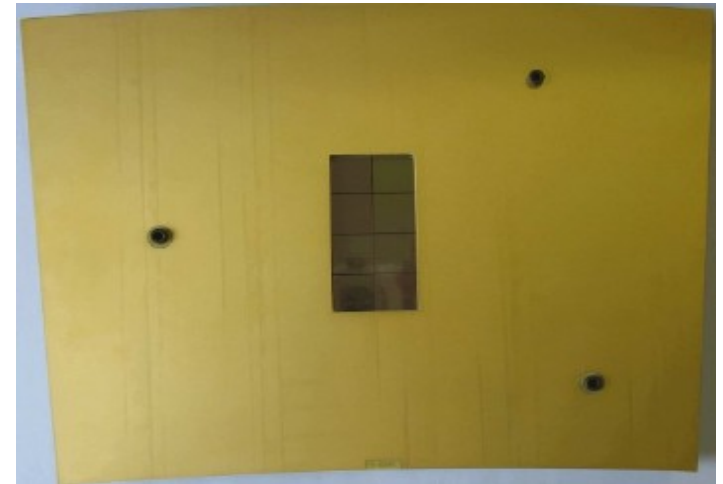
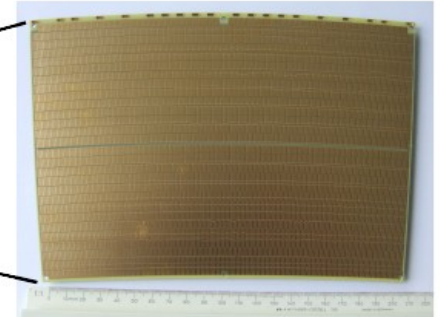
ILD TPC



Large Prototype (LP)



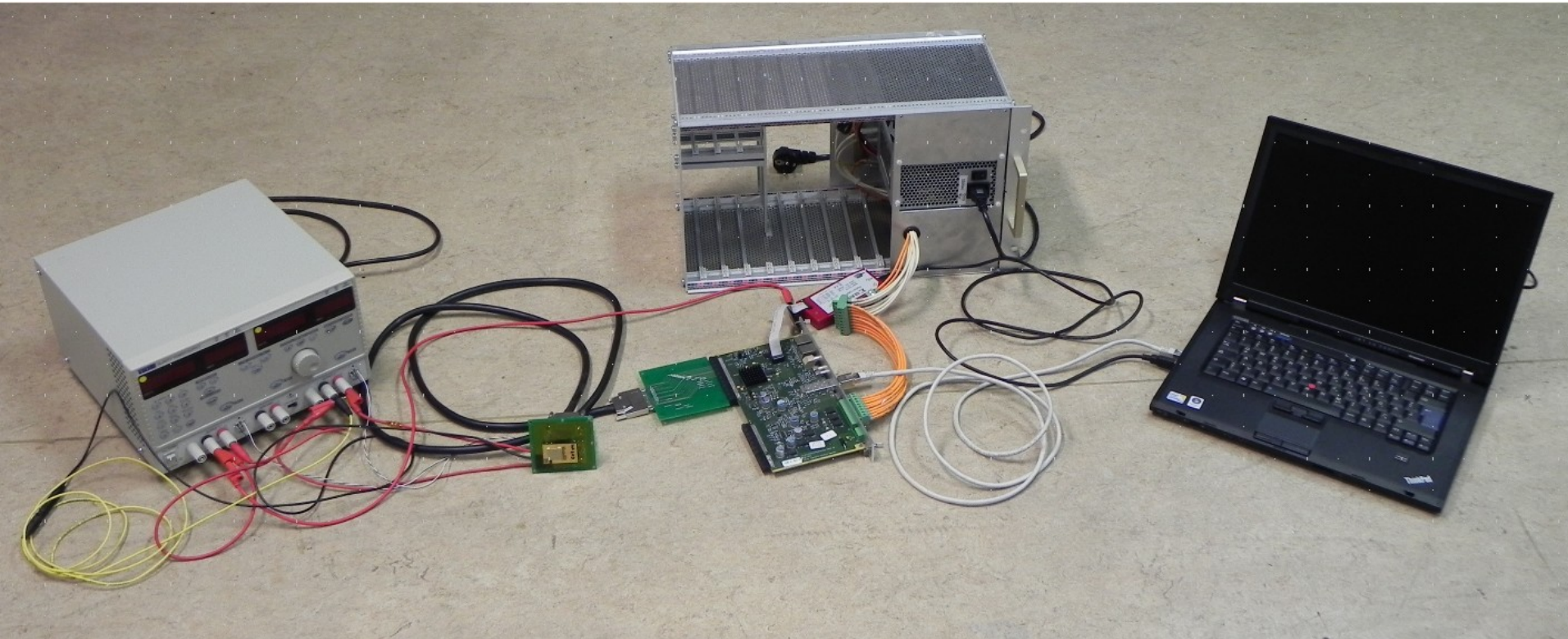
Trapezoid Readout Module
(230 mm × 170 mm)



Status at Testbeam

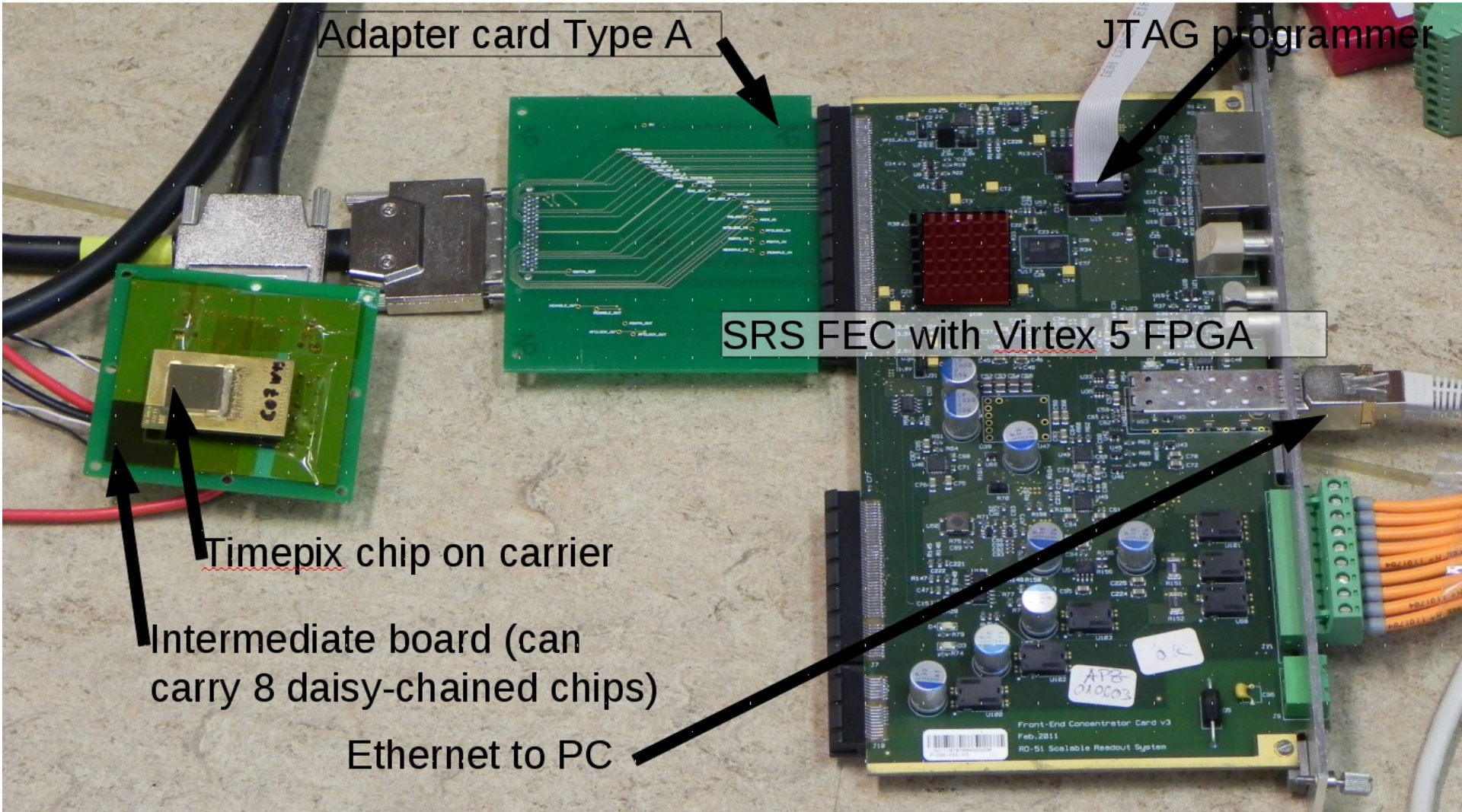


Scalable Readout System (RD51, CERN)



Chain: Chip – Adapter card+FEC – Computer

SRS with Timepix chip



Adapter card Type A

JTAG programmer

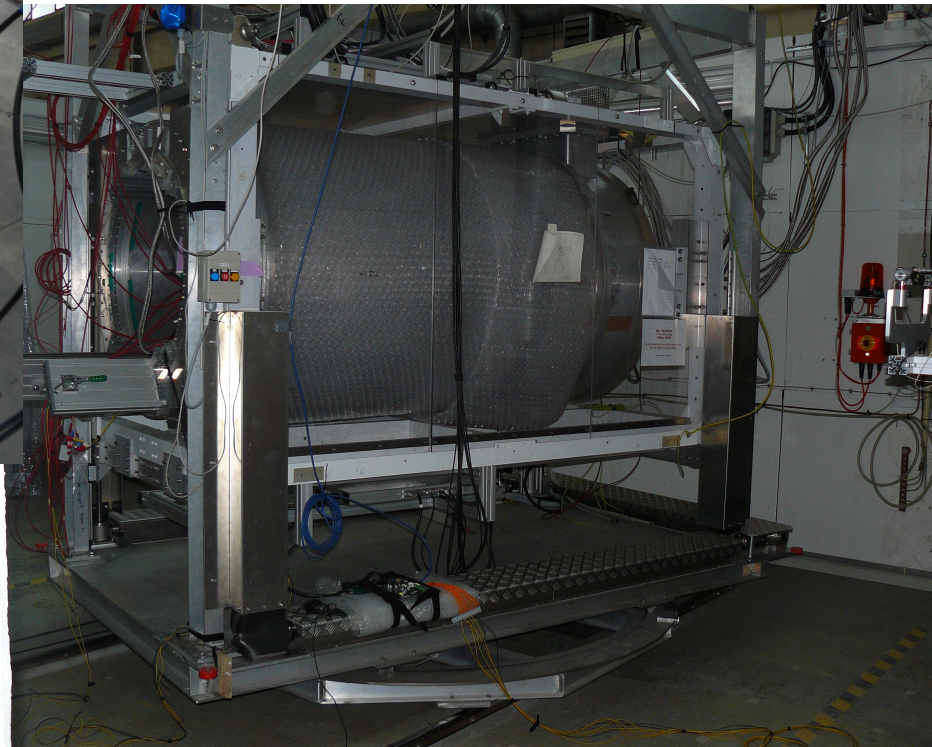
SRS FEC with Virtex 5 FPGA

Timepix chip on carrier

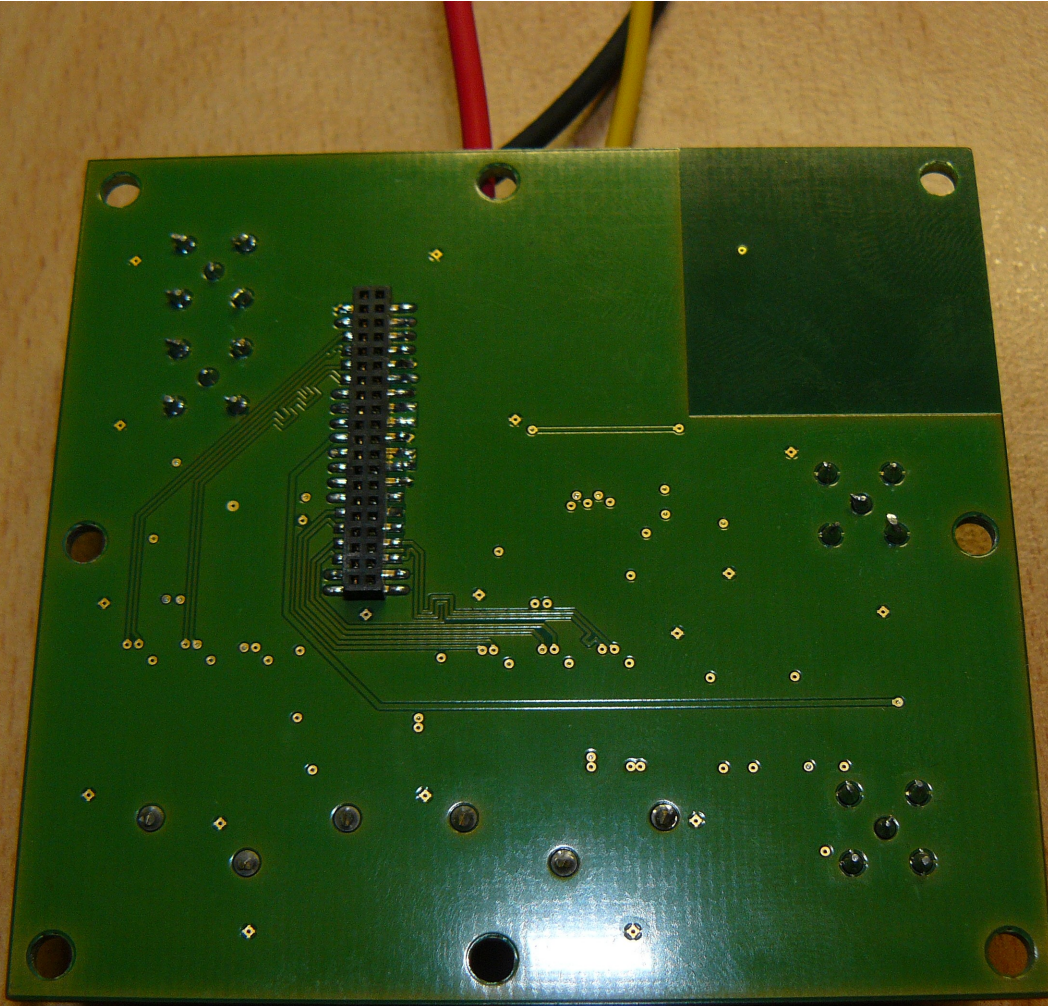
Intermediate board (can carry 8 daisy-chained chips)

Ethernet to PC

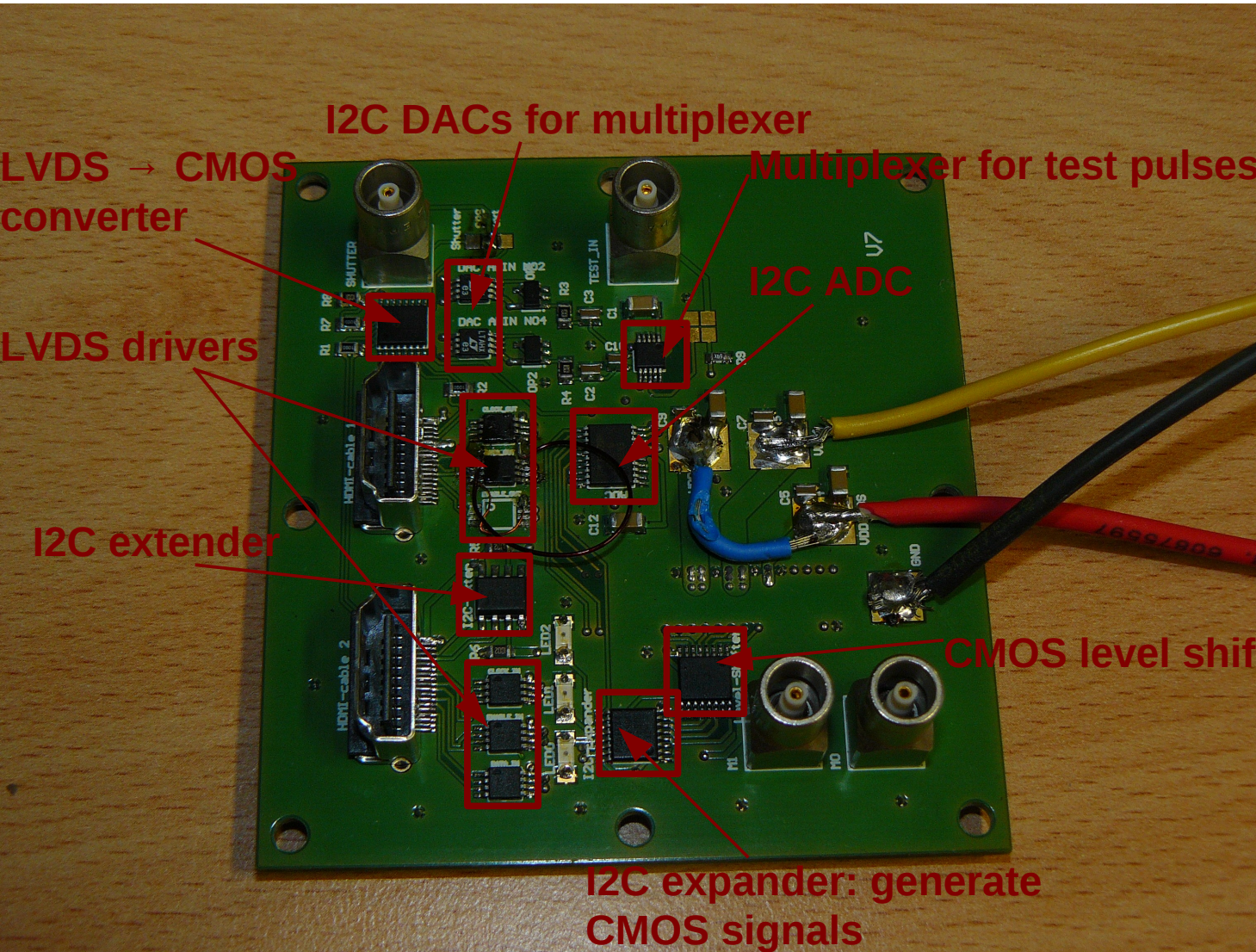
Setup @ testbeam



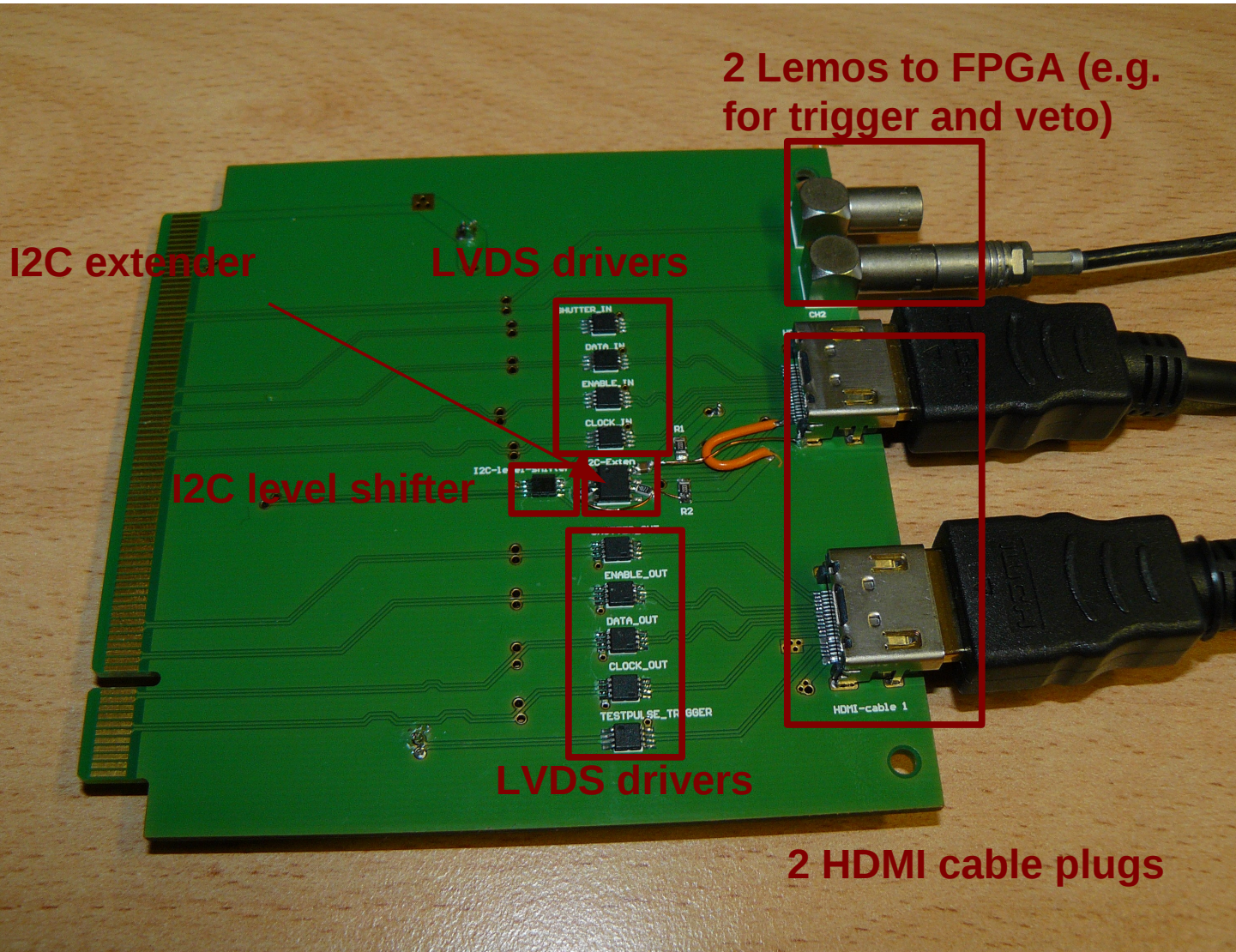
Intermediate board



Intermediate board

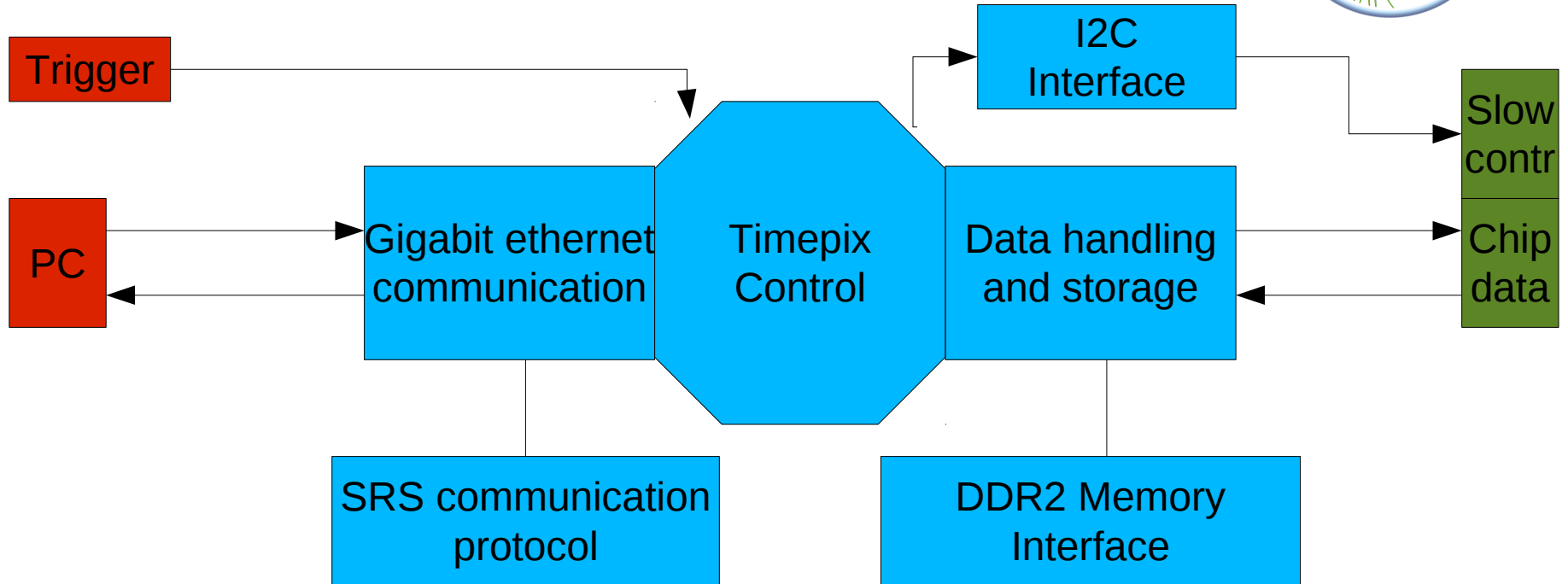


SRS A Card



I2C: standard for small network.
Signals:
scl: clock
sda: data
Originally between PCBs next to each other.
With externs:
Several meters distance.





Some features:

- Multithreading (read chip while sending data of last frame)
- DDR2 RAM to store data of 8 chips
- I2C for slow control

Status Timepix+SRS Readout



- A-Card and intermediate board:
 - HDMI cables
 - Signals optimised for long distance (~25 m)
 - Components on A card and intermediate board:
 - LVDS drivers for long distance
 - I2C network for CMOS signal reduction
 - Remaining CMOS signals transmitted as LVDS and converted to CMOS on intermediate board
 - I2C level shifter and extender for long distance
 - ADC to read back analog signals from Chip (DAC_out)
 - DACs to set voltages for multiplexer
- Latest new parts of FPGA Firmware:
 - I2C Interface
 - DDR2 Interface

Status Timepix+SRS Readout



- Test of components finished
 - I2C network ok (DACs, ADC, expander work)
 - Multiplexer for test pulses ok
 - LVDS driver work => chip can be operated
- Test of FPGA Firmware:
 - DDR2 Ram ok, needs long time testing
 - I2C interface ok
- Software implementation ongoing (e.g. ADC readout, automatic calibration, ...)

Summary and Outlook



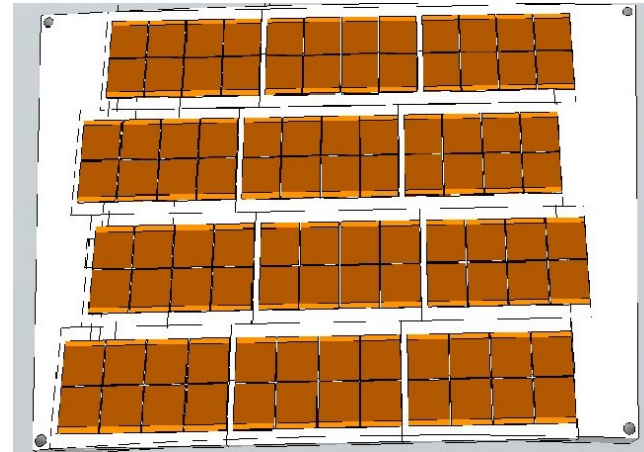
SRS + Timepix readout system hardware components optimised for test beam and about to be finalised.

What is this all for?

Preparation of LCTPC module with ~100 chips

- Scaling up of new hardware
- Want: 3-4 Octoboards/FEC
- Power supply still unsolved

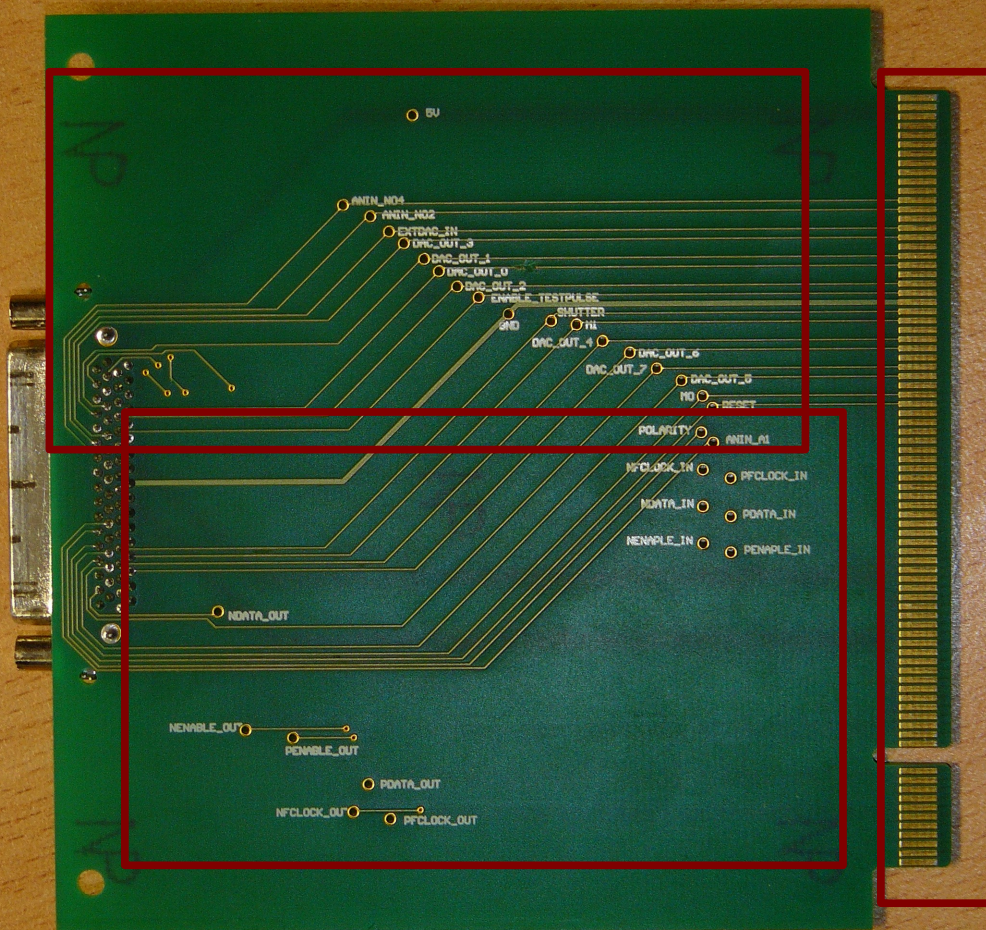
=> Demonstrator for a
pixel TPC (for ILD @ ILC)



A Card



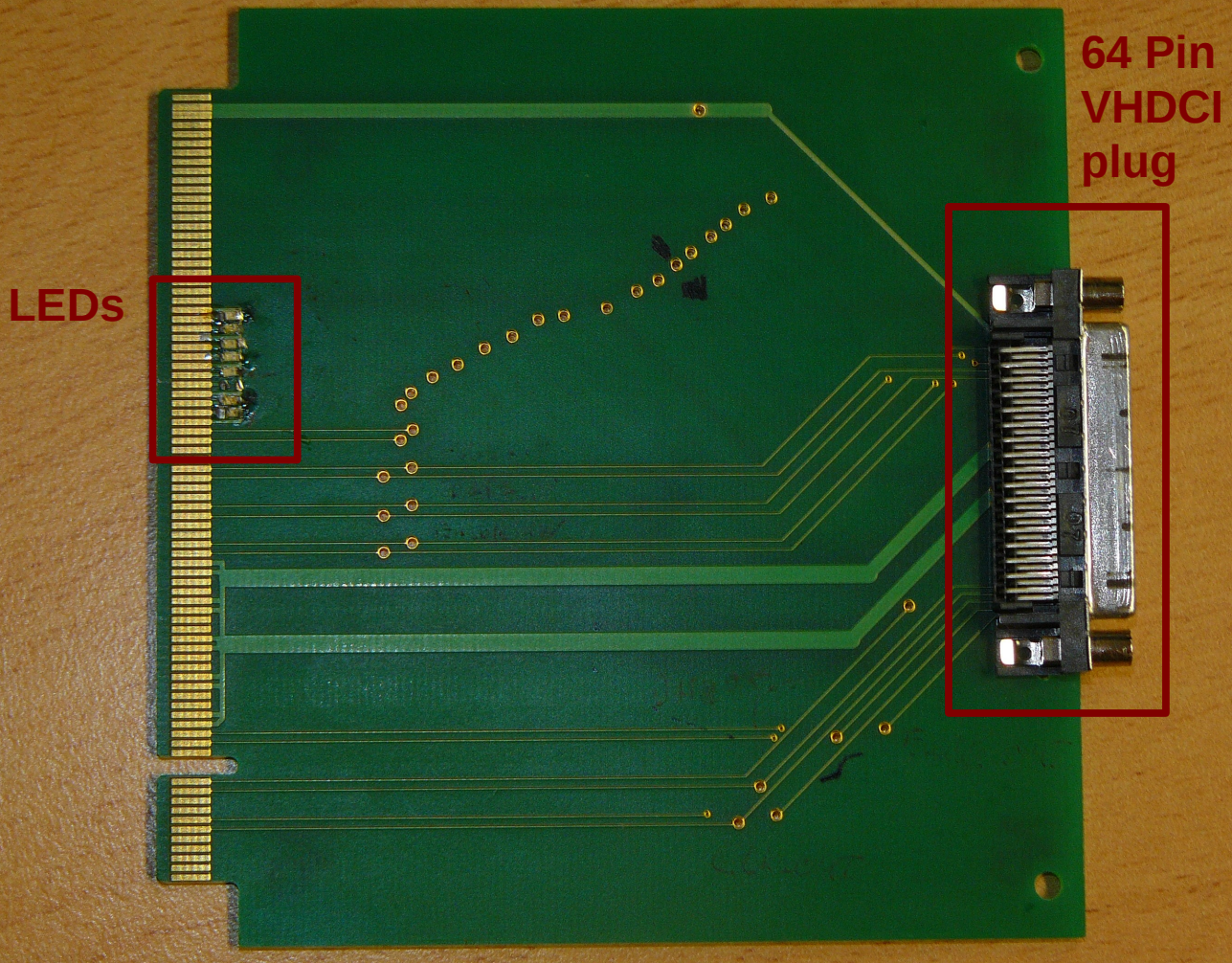
CMOS signals 2.5V



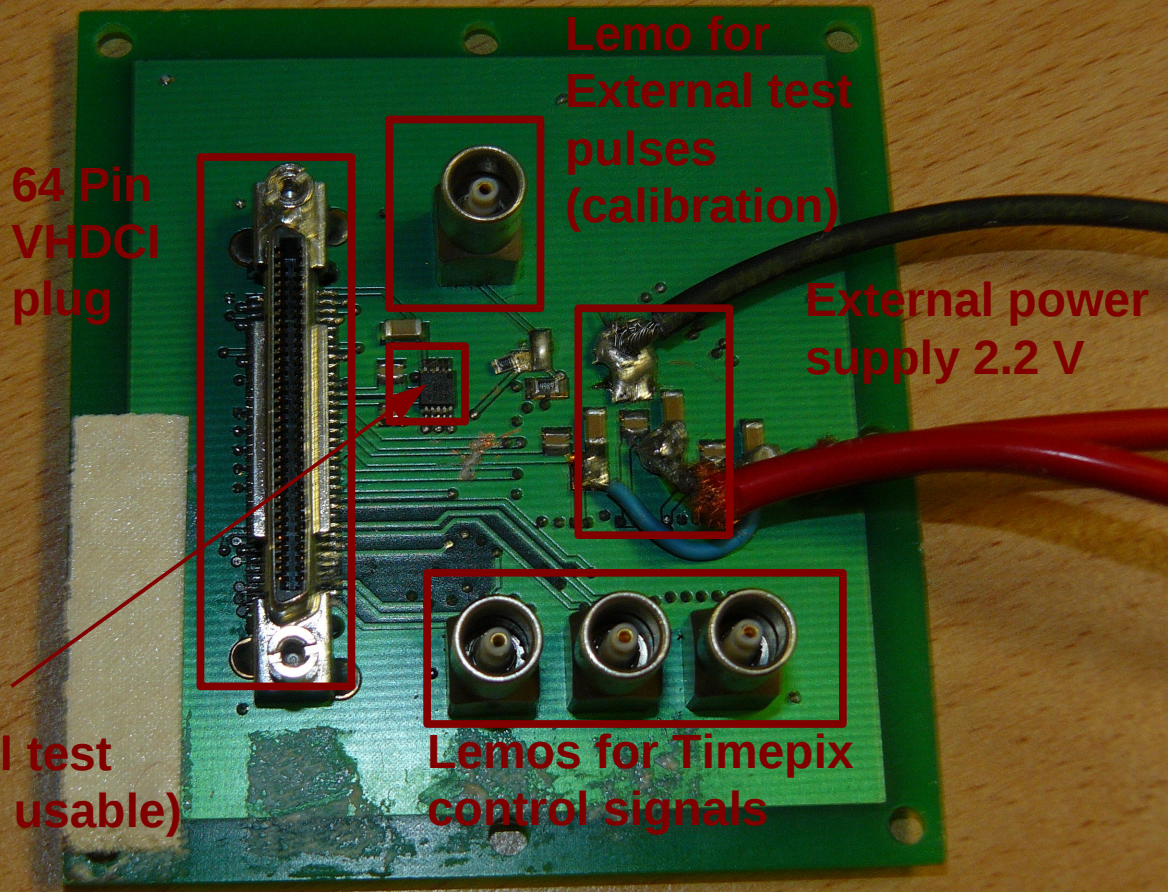
PCI plug to SRS FEC

LVDS signals (differential, p/n)

A Card



Intermediate Board



Multilexer
(for internal test
pulses, not usable)

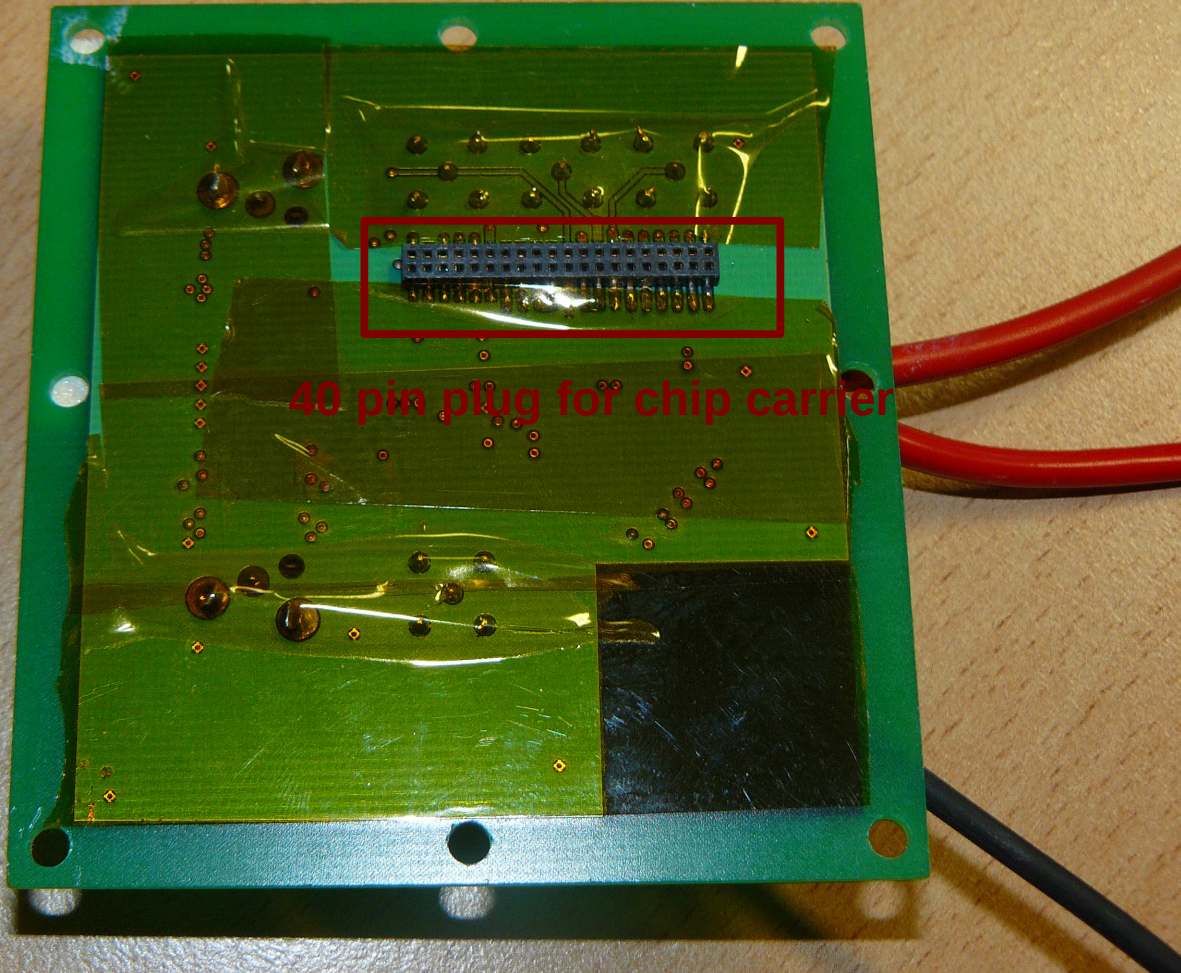
64 Pin
VHDCI
plug

Lemo for
External test
pulses
(calibration)

External power
supply 2.2 V

Lemos for Timepix
control signals

Intermediate Board



40 pin plug for chip carrier

FPGA Firmware

